

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	7664	257/779.ccls. or 257/781-784.ccls. or 257/787-790.ccls. or 257/723.ccls. or 257/734.ccls. or 257/678.ccls.	USPAT	OR	ON	2007/02/16 21:40
L2	68	1 and (foil adj (sheet layer film)) and (chip die component IC (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/16 21:50
L3	57	2 and solder\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 21:50
L4	31	3 and (bond\$3 near pad\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/16 21:40
L5	30	@ad <= "20040324" and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 21:23
L6	37	3 and (bond\$3 near wir\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/16 21:23
L7	36	@ad <= "20040324" and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 21:43
L8	0	(10/807,527).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 21:29

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L9	1	10/807,527	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 21:29
L10	3525	257/779.ccls. or 257/781-784.ccls. or 257/787-790.ccls. or 257/723. ccls. or 257/734.ccls. or 257/678. ccls.	US-PGPUB	OR	ON	2007/02/16 21:40
L11	38	10 and (foil adj (sheet layer film)) and (chip die component IC (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/16 21:40
L12	14	11 and (bond\$3 near pad\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/16 21:42
L13	7	@ad <= "20040324" and 12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 21:41
L14	3717	438/110-114.ccls. or 438/118-119. ccls. or 438/127.ccls.	USPAT	OR	ON	2007/02/16 21:50
L15	41	14 and (foil adj (sheet layer film)) and (chip die component IC (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/16 21:42
L16	18	15 and (bond\$3 near pad\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/16 21:42
L17	18	@ad <= "20040324" and 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 21:50
L18	1435	438/110-114.ccls. or 438/118-119. ccls. or 438/127.ccls.	US-PGPUB	OR	ON	2007/02/16 21:50

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L19	14	18 and (foil adj (sheet layer film)) and (chip die component IC (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/16 21:50
L20	12	19 and solder\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 21:50
L21	7	@ad <= "20040324" and 20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 22:01
S4	292	(foil adj (sheet layer film)) with solder\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 02:56
S5	844	(foil adj (sheet layer film)) with (chip die component IC (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 21:20
S6	58	S4 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 02:57
S7	16	S6 and (bond\$3 near pad\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 21:21
S8	14	@ad <= "20040324" and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 21:22